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PTO/SB/08A (Substitute for form 1449/PTO)				Attorney Docket No.: 023-0025		
				Application No.: 10/774,818		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				First Named Inventor: Mark G. Johnson		
(Use several sheets if necessary)				Filing Date: February 9, 2004		
				Group Art Unit: 2822 2827		
				Examiner Name: Unknown Thongle		
				Date Submitted: February 23, 2005		
U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
TL		US-4,442,507	04/1984	Roesner	—	
		US-5,089,862	02-1992	Warner, Jr. et al.	—	
		US-5,269,852	12-1993	Nishida	—	
		US-5,726,484	03-1998	Hart et al.	—	
		US-5,744,394	04-1998	Iguchi et al.	—	
		US-5,763,299	06-1998	McCollum et al.	—	
		US-5,835,396	11-1998	Zhang	—	
		US-5,937,318	08-1999	Warner, Jr. et al.	—	
		US-5,970,372	10-1999	Hart et al.	—	
		US-5,994,172	11-1999	Ohtani et al.	—	
		US-6,051,851	04-2000	Ohmi et al.	—	
		US-6,124,154	09-2000	Miyasaka	—	
		US-6,420,215 B1	07-2002	Knall et al.	—	
		US-6,436,818 B1	08-2002	Hu et al.	—	
TL		US-6,444,507	09-2002	Miyasaka	—	
FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)	Publication Date MM-DD-YYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	T ⁶
TL		EP 0 800 137 A1	10-1997	Genduso	—	
Examiner Signature		Thongle		Date Considered	12/06/05	

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¹ Applicant's unique citation designation number (optional).

² See Kind Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04.

³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document.

⁵ Kind of document by the appropriate symbol as indicated on the document under WIPO Standard ST.16 if possible.

⁶ Applicant is to place a check mark here if English language translation is attached.

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FORM PTO-1449	SERIAL NO. 10774,818	ATTY. DOCKET NO. 023-0025
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE February 9, 2004	GROUP ART UNIT 2827 -2812
(use several sheets if necessary)		APPLICANT(S): JOHNSON ET AL.

REFERENCE DESIGNATION U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
TL	A1	3,414,892	12/03/1968	MCCORMACK ET AL.		
	A2	3,432,827	03/11/1969	SARNO		
	A3	3,576,549	04/27/1971	HESS ET AL.		
	A4	3,582,908	06/01/1971	KOO		
	A5	3,634,929	01/18/1972	YOSHIDA ET AL.		
	A6	3,717,852	02/20/1973	ABBAS ET AL.		
	A7	3,728,695	04/17/1973	FROHMAN-BENTCHKOWSKY ET AL.		
	A8	3,787,822	01/22/1974	RIOULT		
	A9	3,990,098	11/02/1978	MASTRANGELO		
	A10	4,146,802	03/27/1979	TANIMOTO ET AL.		
	A11	4,203,123	05/13/1980	SHANKS		
	A12	4,203,158	05/13/1980	FROHMAN-BENTCHKOWSKY ET AL.		
	A13	4,281,397	07/28/1981	NEAL ET AL.		
	A14	4,419,741	12/08/1983	STEWART ET AL.		
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	A16	4,494,135	01/15/1985	MOUSSIE		
	A17	4,500,905	02/19/1985	SHIBATA		
	A18	4,507,757	03/26/1985	MCELROY		
	A19	4,535,424	08/13/1985	REID		
	A20	4,543,594	09/24/1985	MOHSEN ET AL.		
	A21	4,589,121	02/11/1986	LIM ET AL.		
	A22	4,630,096	12/16/1986	DRYE ET AL.		
	A23	4,872,577	06/09/1987	HIROSE ET AL.		
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	A29	4,881,114	11/14/1989	MOHSEN ET AL.		
	A30	4,899,205	02/05/1990	HAMDY ET AL.		
	A31	4,922,319	05/01/1990	FUKUSHIMA		
	A32	4,843,538	07/24/1990	MOHSEN ET AL.		
	A33	5,001,539	03/19/1991	INOUE ET AL.		
	A34	5,089,862	02/18/1992	WARNER, JR. ET AL.		
	A35	5,180,987	11/03/1992	PRICER ET AL.		
	A36	5,191,405	03/02/1993	TOMITA ET AL.		
TL	A37	5,202,754	04/13/1993	BERTIN ET AL.		

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
TL	A38	5,266,912	11/30/1993	KLEDZIK		
TL	A39	5,283,468	02/01/1994	KONDO ET AL.		
	A40	5,311,039	05/10/1994	KIMURA ET AL.		
	A41	5,334,880	08/02/1994	ABADEER ET AL.		
	A42	5,391,518	02/21/1995	BHUSHAN		
	A43	5,398,200	03/14/1995	MAZURE ET AL.		
	A44	5,422,435	06/08/1995	TAKIAR ET AL.		
	A45	5,426,666	08/20/1995	BEILSTEIN, JR. ET AL.		
	A46	5,434,745	07/18/1995	SHOKRGOZAR ET AL.		
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	A52	5,481,133	01/02/1996	H8U		
	A53	5,485,398	02/27/1996	TAKIAR ET AL.		
	A54	5,502,289	03/26/1996	TAKIAR ET AL.		
	A55	5,523,622	06/04/1996	HARADA ET AL.		
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	A57	5,535,158	07/09/1996	LEVY ET AL.		
	A58	5,536,888	07/16/1996	CRAFTS ET AL.		
	A59	5,552,963	09/03/1996	BURNS		
	A60	5,561,622	10/01/1996	BERTIN ET AL.		
	A61	5,581,498	12/03/1996	LUDWIG ET AL.		
	A62	5,586,675	12/17/1996	KNOPF		
	A63	5,612,570	03/18/1997	EIDE ET AL.		
	A64	5,654,220	08/05/1997	LEEDY		
	A65	5,675,547	10/07/1997	KOGA		
	A66	5,686,341	11/11/1997	ROESNER		
	A67	5,693,652	12/02/1997	Hsu		
	A68	5,696,031	12/09/1997	WARK		
	A69	5,703,747	12/30/1997	VOLDMAN ET AL.		
	A70	5,737,259	04/07/1998	CHANG		
	A71	5,751,012	05/12/1998	WOLSTENHOLME ET AL.		
	A72	5,778,810	07/07/1998	GUTERMAN ET AL.		
	A73	5,780,925	07/14/1998	CIPOLLA ET AL.		
	A74	5,781,031	07/14/1998	BERTIN ET AL.		
	A75	5,801,437	09/01/1998	BURNS		
TL	A76	5,883,409	03/16/1999	GUTERMAN ET AL.		

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REFERENCE DESIGNATION U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
TL	A77	5,915,167	06/22/1999	LEEDY		
	A78	5,989,380	10/19/1999	SEYYEDY		
	A79	5,976,953	11/02/1999	ZAVRACKY ET AL.		
	A80	5,985,693	11/16/1999	LEEDY		
	A81	6,057,598	05/02/2000	PAYNE ET AL.		
	A82	6,072,234	06/08/2000	CAMEN ET AL.		
	A83	6,087,722	07/11/2000	LEE ET AL.		
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	A85	6,185,122 B1	02/08/2001	JOHNSON ET AL.		
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	A87	6,208,646 B1	03/27/2001	LEEDY		
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	A90	6,307,257 B1	10/23/2001	HUANG ET AL.		
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	A92	6,314,013 B1	11/06/2001	AHN ET AL.		
	A93	6,322,903 B1	11/27/2001	SINIAGUINE ET AL.		
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	A95	6,337,521 B1	01/08/2002	MASUDA		
	A96	6,351,028 B1	02/26/2002	AKRAM		
	A97	6,353,285 B1	03/05/2002	MICHII		
	A98	6,355,601 B1	03/12/2002	FUNG ET AL.		
	A99	US2002/0024146 A1	02/28/2002	FURUSAWA		
	A100	US2002/0027275 A1	03/07/2002	FUJIMOTO ET AL.		
	A101	US2002/0030262 A1	03/14/2002	AKRAM		
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	A103	3,671,848	06/20/72	CASSEN ET AL.		
	A104	5,070,383	12/91	SINAR ET AL.		
	A105	5,391,917	2/95	GILMOUR ET AL.		
	A106	5,854,534	12/98	BEILIN ET AL.		
	A107	5,903,059	5/99	BERTIN ET AL.		
	A108	5,980,539	10/99	BURNS		
	A109	5,978,258	11/99	MANNING		
	A110	6,049,123	4/00	BURNS		
	A111	3,863,231	1/75	TAYLOR		
	A112	4,229,757	10/80	MOUSSIE		
TL	A113	5,103,422	4/82	TOKITA ET AL.		

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
TL	A114	4,855,953	8/89	TSUKAMOTO ET AL.		
	A115	5,436,861	7/95	KATTI ET AL.		
	A116	5,289,410	2/94	KATTI ET AL.		
	A117	4,272,880	8/16/1981	PASHLEY		
	A118	4,442,507	4/10/1984	ROESNER		
	A119	4,489,478	12/25/1984	SAKURA		
	A120	4,498,228	2/12/1985	INOUE ET AL.		
	A121	4,499,557	2/12/1985	HOLMBERG ET AL.		
	A122	4,646,268	2/24/1987	OVSHINGSKY ET AL.		
	A123	4,677,742	7/7/1987	JOHNSON		
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	A127	5,441,907	8/15/1995	SUNG ET AL.		
	A128	5,602,987	2/11/1997	HARARI ET AL.		
	A129	5,640,343	6/17/1997	GALLAGHER ET AL.		
	A130	5,745,407	4/28/1998	LEVY ET AL.		
	A131	5,835,396	11/10/1998	ZHANG		
	A132	5,929,478	7/27/1999	PARRIS ET AL.		
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TL	A134	6,034,882	3/7/00	JOHNSON ET AL.		

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TL	A135	EP 0 073 488 A2	03/09/1983	Europe		X
	A136	JP 60-22352 A	02/04/1985	Japan		Abstract
	A137	JP 61222216 A	10/02/1986	Japan		Abstract
	A138	JP 63-52463 A	03/05/1988	Japan		Abstract
	A139	EP 0 387 834 A2	09/19/1990	Europe		X
	A140	EP 0 385 888 A2	11/07/1990	Europe		X
	A141	EP 0 516 888 A1	12/09/1992	Europe		X
	A142	EP 0 606 653 A1	07/20/1994	Europe		X
TL	A143	WO 94/26083	11/10/1994	WIPO		X

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EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES NO
TL	A144	EP 0 644 548 A2	03/22/1995	Europe		X
TL	A145	EP 0 516 868 A1	12/09/1992	Europe		X
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	A148	Akasaka, Yoichi, "Three-Dimensional IC Trends," Proceedings of the IEEE, Vol. 74, No. 12, December 1986, pages 1703 - 1714
	A149	Berlin, Claude L., "Evaluation of a Three-Dimensional Memory Cube System," IEEE Transactions on Components, Hybrids, and Manufacturing Technology, Vol. 16, No. 8, December 1993, 1006 - 1011
	A150	Camperi-Ghestet, C., "Vertical Electrical Interconnection of Compound Semiconductor Thin-Film Devices to Underlying Silicon Circuitry," IEEE Photonics Technology Letters, Vol. 4, No. 9, September 1992, pages 1003 - 1006
	A151	Frohman-Bentchkowsky, Dov, "A Fully Decoded 2048-Bit Electrically Programmable FAMOS Read-Only Memory," IEEE Journal of Solid-State Circuits, Vol. SC-8, No. 5, October 1971, pages 301 - 306
	A152	Hayashi, Y., "A New Three Dimensional IC Fabrication Technology, Stacking Thin Film Dual-CMOS Layers," IEDM 1991, pages 657 - 660
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	A155	Inoue, Y., "A Three-Dimensional Static RAM," IEEE Electron Device Letters, Vol. Edl-7, No. 5, May 1986, pages 327 - 329
	A156	Jokersl, N.M., "Manufacturable Multi-Material Integration Compound Semiconductor," SPIE - The International Society for Optical Engineering, Vol. 2524, July 11 - 12, 1995, pages 152 - 163
	A157	Kurokawa, Takakazu, "3-D VLSI Technology In Japan and an Example: A Syndrome Decoder for Double Error Correction," Future Generations Computer Systems 4, No. 2, September 1988, pages 145 - 155
	A158	Lay, Richard W., "TRW Develops Wireless Multiboard Interconnect System," Electronic Engineering Times, November 5, 1984
	A159	Mallniak, David, "Memory-Chip Stacks Send Density Skyward," Electronic Design 42, No. 17, August 22, 1994, pages 69 - 75
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(use several sheets if necessary)		APPLICANT(S): JOHNSON ET AL.

EXAMINER INITIAL	OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)	
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	A162	Sakamoto, Koji, "Architecture of Three Dimensional Devices," Bulletin of The Electrotechnical Laboratory, Vol. 51, No. 1, 1987, pages 16 - 29
	A163	Sato, Noriaki, et al., "A New Programmable Cell Utilizing Insulator Breakdown," IEAM Technical Digest, 1985, pages 639 - 642
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	A167	Stern, Jon M., "Design and Evaluation of an Epoxy Three-Dimensional Multichip Module," IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part B, Vol. 19, No. 1, February 1996, pages 188 - 194
	A168	Terrill, Rob, "3D Packaging Technology Overview and Mass Memory Applications," IEEE 1996, pages 347 - 355
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	A178	"Module Pack Pairs Cubic Memory with VisionTek," Semiconductor Industry & Business Survey, v17, n15, pN/A October 23, 1995
	A179	"Layers of BST Materials Push Toward 1Gbit DRAM," Electronics Times, p 10, October 19, 1995
	A180	"Technologies Will Pursue Higher DRAM Densities," Electronic News (1991), p 12 December 5, 1994
TL	A181	"Looking for Diverse Storage," Electronic Engineering Times, p 44 October 31, 1994

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EXAMINER INITIAL	OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)	
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TL	A183	"Technique Boosts 3D Memory Density," Electronic Engineering Times p 16 August 29, 1994
TL	A184	"Memory Packs Poised for 3D Use," Electronic Engineering Times p 82 December 7, 1992
TL	A185	"MCMs Hit the Road," Electronic Engineering Times p 45 June 15, 1992
TL	A186	"IEDM Ponders the "Gigachip" Era," Electronic Engineering Times, p 33 January 20, 1992
TL	A187	"Tech Watch: 1-Gbit DRAM In Sight," Electronic World News, p 20 December 16, 1991
TL	A188	"MCMs Meld Into Systems," Electronic Engineering Times p 35 July 22, 1991
TL	A189	"Systems EEs see Future in 3D," Electronic Engineering Times p 37 September 24, 1990
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TL	A191	Kawashima et al., "A Charge-Transfer Amplifier and an encoded-Bus Architecture for Low-Power SRAM," <i>IEEE Journal of Solid-State Circuits</i> , 33, No. 5, 793-799 (1998)
TL	A192	Cappelletti et al., "Flash Memories", Kluwer Academic Publishers, Table of Contents, pp. 47, pp. 308 (1999)
TL	A193	"Three-Dimensional Read-Only Memory (3D-ROM)" [online] [retrieved on 8/10/00] retrieved from the Internet: <URL: http://sites.netscape.net/zhangpatents/3D-ROM/3D-ROM.htm
TL	A194	Semiconductor International, "3D-ROM-A First Practical Step Towards 3D-IC" [online] [retrieved on 8/10/00] retrieved from the Internet: <URL: http://www.semiconductor.net/semiconductor/issues/webexclusives/200.../six000633DROM.as

EXAMINER <i>Wioyle</i>	DATE CONSIDERED <i>12/06/05</i>
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

